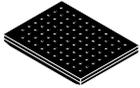


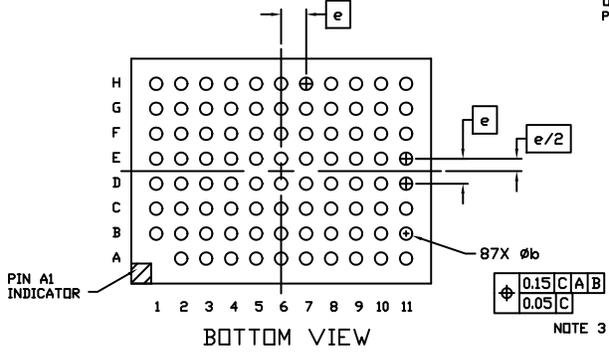
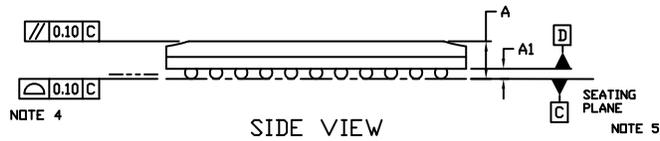
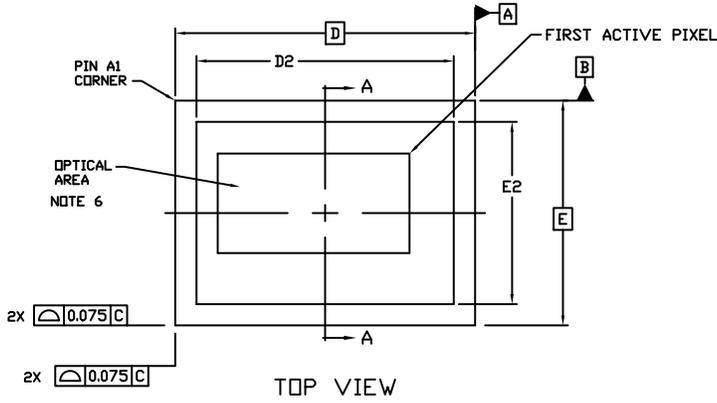
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

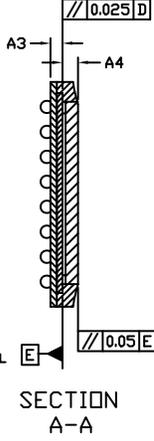


IBGA87 12x9
CASE 503BF
ISSUE B

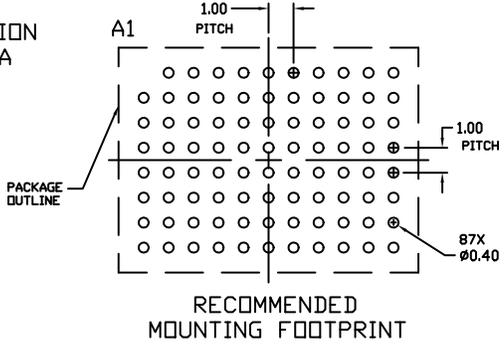
DATE 08 AUG 2017



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
 7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
 8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS x=-462.70 MICRONS, Y=389.80 MICRONS ±75 MICRONS.



DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.65
A1	0.35	0.45
A3	0.425	0.525
A4	0.575	0.675
b	0.45	0.55
D	12.00 BSC	
D2	10.20	10.40
E	9.00 BSC	
E2	7.20	7.40
e	1.00 BSC	



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